



60V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)} Max	I _D Max @ T _A = +25°C	
60V	1.4Ω @ V _{GS} = 10V	0.41A	
	1.6Ω @ V _{GS} = 4.5V	0.38A	

Description

This MOSFET has been designed to minimize the on-state resistance $(R_{DS(ON)})$ and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Load Switch
- Portable Applications
- Power Management Functions

Features and Benefits

- Footprint of just 0.6mm² thirteen times smaller than SOT23
- Low On-Resistance
- Low Gate Threshold Voltage
- · Fast Switching Speed
- Ultra-Small Surface Mount Package
- ESD Protected Gate 200V
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

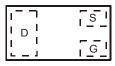
Mechanical Data

- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.001 grams (approximate)

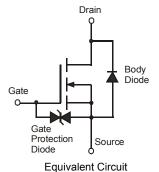
X1-DFN1006-3



Bottom View



Top View Internal Schematic



Ordering Information (Note 4)

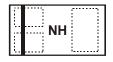
Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMN62D1SFB-7B	NH	7	8	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

DMN62D1SFB-7B



Top View Bar Denotes Gate and Source Side

NH = Product Type Marking Code



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Character	istic		Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	60	V
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 5) $V_{GS} = 10V$ $T_A = +25^{\circ}C$ $T_A = +85^{\circ}C$		I _D	0.41 0.30	А	
Pulsed Drain Current (Note 6)			I _{DM}	2.64	Α

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Power Dissipation (Note 5)		P_{D}	0.47	W
Thermal Resistance, Junction to Ambient @T _A =+25°C		$R_{\theta JA}$	258	°C/W
Operating and Storage Temperature Range		T_{J}, T_{STG}	-55 to +150	°C

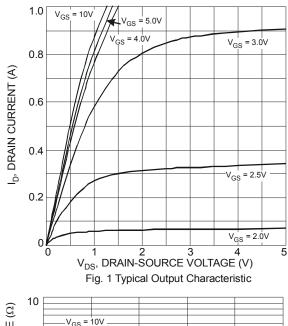
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

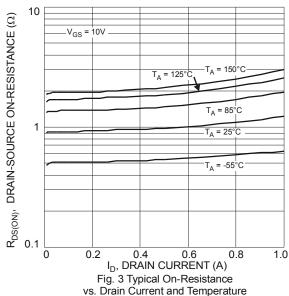
Characteristic	Symbol	Min	Тур	Max	Unit	Tes	st Condition	
OFF CHARACTERISTICS (Note 7)								
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	V _{GS} = 0V, I _D = 250μA		
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	100	nA	V _{DS} = 60V,	V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	10 1	μA	V _{GS} = ±20V, V _{DS} = 0V V _{GS} = ±5V, V _{DS} = 0V		
ON CHARACTERISTICS (Note 7)								
Gate Threshold Voltage	$V_{GS(th)}$	1.3	1.6	2.3	V	$V_{DS} = V_{GS}$	I _D = 250μA	
Statia Drain Sauras On Besistanes)			1.40	Ω	V _{GS} = 10V,	V _{GS} = 10V, I _D = 40mA	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	_	1.60		$V_{GS} = 4.5V$,	I _D = 35mA	
Forward Transfer Admittance	Y _{fs}	100	_	_	mS	V _{DS} = 5V, I _D = 40mA		
Diode Forward Voltage	V_{SD}	_	0.7	1.1	V	V _{GS} = 0V, I _S = 300mA		
DYNAMIC CHARACTERISTICS (Note 8)								
Input Capacitance	C _{iss}	_	40	80	pF	10)(
Output Capacitance	Coss	_	3.5	7	pF	$V_{DS} = 40V, Y_{DS}$	$V_{GS} = 0V$,	
Reverse Transfer Capacitance	C _{rss}	_	2.8	5.6	pF	1 - 1.0101112		
Gate Resistance	Rg	_	81.3	200	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz		
Total Gate Charge	Qg	_	0.73	1.5	nC	V _{GS} = 4.5V		
Total Gate Charge	Q_g	_	1.39	2.8	nC	$V_{GS} = 10V$ $V_{DS} = 50V, I_D = 1A$		
Gate-Source Charge	Q _{gs}	_	0.2	0.4	nC			
Gate-Drain Charge	Q _{gd}	_	0.23	0.5	nC			
Turn-On Delay Time	t _{D(on)}		3.89	10	ns	V_{DS} = 50V, I_{D} = 1A V_{GS} = 10V, R_{G} = 6 Ω		
Turn-On Rise Time	t _r		4.93	10	ns			
Turn-Off Delay Time	t _{D(off)}		18.80	40	ns			
Turn-Off Fall Time	t _f	_	11.96	25	ns			

Notes:

- 5. Device mounted on FR-4 PCB, with minimum recommended pad layout.
- 6. Device mounted on minimum recommended pad layout test board, 10µs pulse duty cycle = 1%.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to production testing.







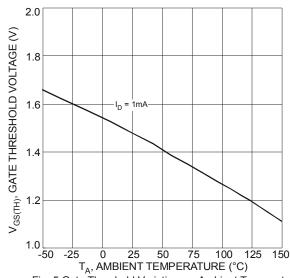


Fig. 5 Gate Threshold Variation vs. Ambient Temperature

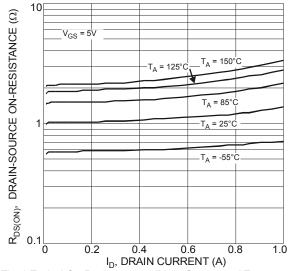


Fig. 2 Typical On-Resistance vs. Drain Current and Temperature

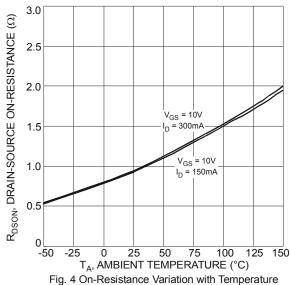


Fig. 4 On-Resistance Variation with Temperature

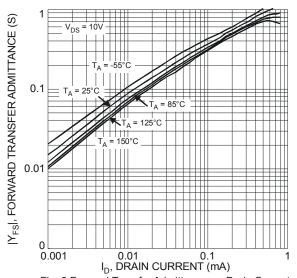
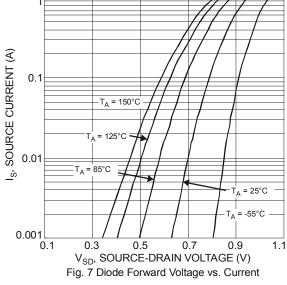
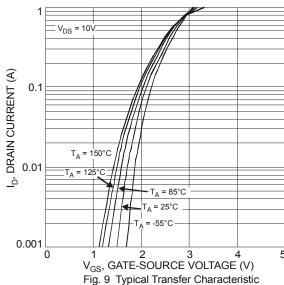
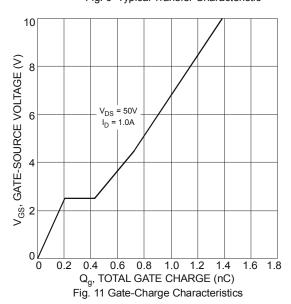


Fig. 6 Forward Transfer Admittance vs. Drain Current









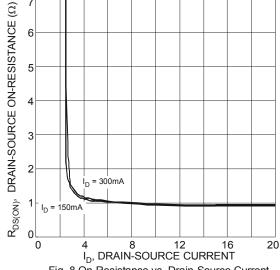
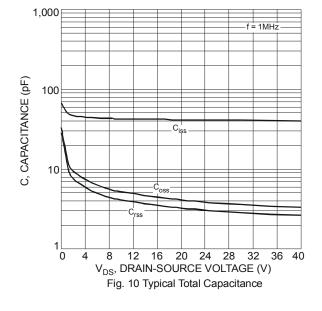
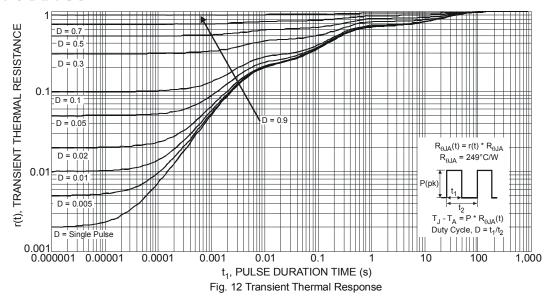


Fig. 8 On-Resistance vs. Drain-Source Current

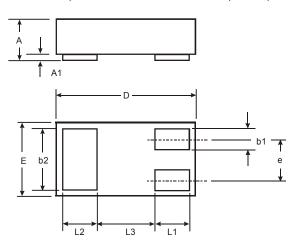






Package Outline Dimensions

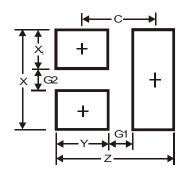
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



X1-DFN1006-3					
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0	0.05	0.03		
b1	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.075	1.00		
Е	0.55	0.675	0.60		
e			0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3	_	_	0.40		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
Х	0.7
X1	0.25
Υ	0.4
С	0.7



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